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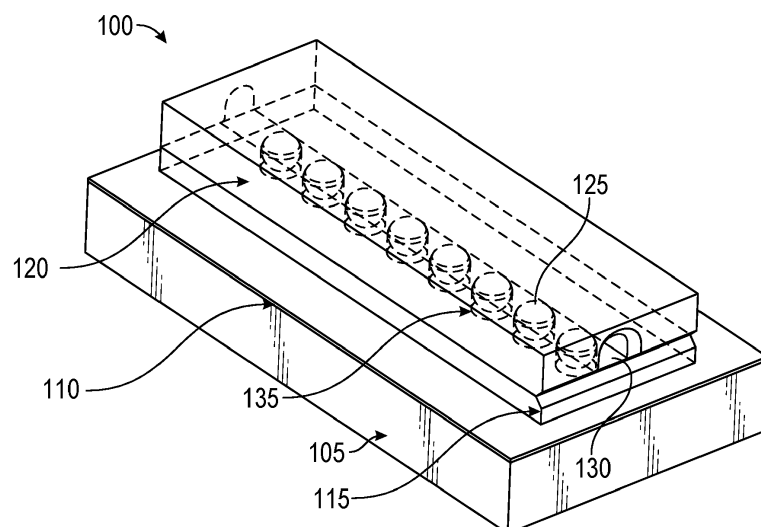
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(54) **MEDICAL LEAD CONNECTORS WITH CONTACT ELECTRODES**

(57) Embodiments disclosed herein include devices and methods pertaining to medical lead connectors. According to various embodiments of the disclosed technology, disclosed is a lead connector (100) that may include a base member (105); a flexible circuit (110) configured to support electrical connections; and a casing that includes a bottom casing (115) and a detachable cover member (120) to be placed on top of the bottom casing (115). The bottom casing (115) may include an array of slot openings to provide access to a surface of

the flexible circuit (110) and the lead connector (100) may also include an array of electrode contacts (125) positioned on top of the slot openings. Furthermore, a lead may be configured to be inserted through the lead connector (100) via an opening (130) on both ends of the cover member (120), wherein the lead pushes the ball contacts (125) downward allowing the ball contacts (125) to make electrical contact with the flexible circuit (110) through the slot opening of the bottom casing (115).



**FIG. 1A**

## Description

### Technical Field

[0001] The disclosed technology relates generally to lead connectors, and more particularly, some embodiments relate to lead connectors with contact electrodes for medical use.

### Background

[0002] Electrodes used in medical devices transfer ionic current energy into electrical current, where such currents can be amplified and be applied for various medical applications. For example, the electrodes may be applied to help diagnose various diseases, monitor the human body for specific conditions, and even facilitate medical operations during complex surgeries. Indeed, such electrodes are even known to help provide medical treatment for patients with Parkinson's disease, Alzheimer's disease, sinus, body ache, epilepsy, heart conditions, and other various medical conditions.

### Brief Summary of Embodiments

[0003] According to various embodiments of the disclosed technology, disclosed is a lead connector that may include a base member; a flexible circuit configured to support electrical connections; and a casing that includes a bottom casing and a detachable cover member to be placed on top of the bottom casing. The bottom casing may include an array of slot opening to provide access to a surface of the flexible circuit and the lead connector may include an array of electrode contacts positioned on top of the slot openings within the bottom casing. Furthermore, the lead connector may receive a lead that is configured to be inserted through the lead connector via an opening on both ends of the cover member, wherein the lead pushes the ball contacts downward to make electrical contact with the flexible circuit through the slot opening of the bottom casing.

[0004] Other features and aspects of the disclosed technology will become apparent from the following detailed description, taken in conjunction with the accompanying drawings, which illustrate, by way of example, the features in accordance with embodiments of the disclosed technology. The summary is not intended to limit the scope of any inventions described herein, which are defined solely by the claims attached hereto.

### Brief Description of the Drawings

[0005] The technology disclosed herein, in accordance with one or more various embodiments, is described in detail with reference to the following figures. The drawings are provided for purposes of illustration only and merely depict typical or example embodiments of the disclosed technology. These drawings are provided to fa-

cilitate the reader's understanding of the disclosed technology and shall not be considered limiting of the breadth, scope, or applicability thereof. It should be noted that for clarity and ease of illustration these drawings are not necessarily made to scale.

[0006] Some of the figures included herein illustrate various embodiments of the disclosed technology from different viewing angles. Although the accompanying descriptive text may refer to such views as "top," "front," "back," "bottom" or "side" views, such references are merely descriptive and do not imply or require that the disclosed technology be implemented or used in a particular spatial orientation unless explicitly stated otherwise.

FIG. 1A is a diagram illustrating a lead connector without a lead inserted in accordance with one embodiment of the technology described herein.

FIG. 1B is a diagram illustrating a cross-sectional view of a lead connector without a lead inserted in accordance with one embodiment of the technology described herein.

FIG. 2 is a diagram illustrating a ball contact within a lead connector in accordance with one embodiment of the technology described herein.

FIG. 3A is a diagram illustrating a lead connector with a lead inserted in accordance with one embodiment of the technology described herein.

FIG. 3B is a diagram illustrating a cross-sectional view of a lead connector with a lead inserted in accordance with one embodiment of the technology described herein.

FIG. 4 is a diagram illustrating a lead connector in contact with a lead in accordance with one embodiment of the technology described.

FIG. 5 is a diagram illustrating a lead connector with a lead inserted in accordance with one embodiment of the technology described herein.

FIG. 6 is a diagram illustrating a lead connector in contact with a lead inserted in accordance with one embodiment of the technology described.

FIG. 7 is a diagram illustrating a lead connector 700 with springs below the metal ball contacts 710 in accordance with one embodiment of the technology described.

[0007] The figures are not intended to be exhaustive or to limit the invention to the precise form disclosed. It should be understood that the invention can be practiced with modification and alteration, and that the disclosed

technology be limited only by the claims and the equivalents thereof.

### Detailed Description of the Embodiments

**[0008]** Embodiments of the technology disclosed herein are directed toward an apparatus pertaining to medical lead connectors with contact electrodes. In various embodiments, a lead wire, which may be a multi-conductor lead, includes a plurality of lead contacts disposed along the lead. The lead contacts are dimensioned and spaced apart such that when the lead is inserted into the lead connector, the lead contacts align with corresponding lead connector contacts in the lead connector housing. The lead is of a shape and diameter to be inserted in the lead connector housing, and the lead connector housing can be shaped such that it guides the lead to a position in which the lead contacts are aligned and in physical contact with the corresponding electrical contacts on the lead connector, thereby establishing an electrical connection.

**[0009]** The electrical contacts on the lead connector can be in the form of floating contacts that deflect to allow insertion of the lead into the lead connector housing, but that also spring back to provide good electrical contact to their corresponding lead contacts. In some embodiments, the lead connector contacts are mounted on and electrically connected to a flexible circuit board, such that the circuit board can flex to allow the lead contacts to deflect. The flexible circuit board can be mounted on an elastomeric material such as a foam or foam-like substrate to support the circuit board, allow it to flex and also provide pressure to force the lead connector contacts toward the lead contacts. The properties of the elastomeric substrate can be selected such that it provides sufficient pressure to allow good electrical contact between the connector contacts and their respective lead contacts. In further embodiments, the elastomeric substrate can be selected such that it provides sufficient friction to hold the lead in place in the connector body during use. In some applications, the lead connectors can be configured as disposable items that can be slid into place on the leads for use and then removed from the leads and discarded after use. An elastomeric substrate not only provides pressure for a good electrical connection, but can also allow the lead connector to flex during use, which can be an advantage in certain applications such as medical applications and other applications across various industries.

**[0010]** Figure 1A is a diagram illustrating a lead connector 100 in accordance with one embodiment of the technology described herein. Additionally, Figure 1B is a diagram illustrating a cross-sectional view of the example lead connector 100 illustrated in Figure 1A.

**[0011]** Referring now to Figures 1A and 1B, the example lead connector may include at least a base member 105, a flexible circuit 110, bottom casing 115, cover member 120, and lead connector contacts 125. The base

member 105 may be made of an elastomeric material by way of example only. Additionally, the base member 105 may be made of any material with sufficient elastic properties to allow the base member 105 to be bent, stretched, twisted, or deformed, and when released, return to its original shape and dimensions. The elastic properties of the base material may be selected to allow the base to conform to the surface to which it is applied, flex sufficiently to allow a lead to be inserted into opening 130 located on either or both sides of cover member 120, and spring back with sufficient force to allow the lead connector contacts 125 to make sufficient electrical contact with the lead contacts. However, base member 105 may be made of any material as would be appreciated by one of ordinary skill in the art.

**[0012]** A flexible circuit 110 may be mounted on the top surface of the base member 105. The flexible circuit 110 may include one or more layers of printed circuit connections and contacts, including traces that may be connected to or in contact with the lead connector contacts 125. As such, the flexible circuit 110 and the underlying base member 105 may support the mechanical and electrical connections needed to ensure that the proper electrical connections are made so that electronic or medical devices may be supported when connected to the lead connector 100. By way of further example, the flexible circuit 110 may be designed to flex and bend as the base member 105 flexes and bends, so that both the flexible circuit 110 and the base member 105 may experience the same or near identical movement or conformed shape.

**[0013]** In the illustrated example, lead connector contacts 125 are in the form of ball contacts, which may be made of or coated with a conductive material such as, for example, gold, silver, copper, graphite, platinum, tin, carbon, conductive polymers, or other conductive materials. In other embodiments, lead connector contacts 125 are in the form of solder bumps or balls or other like structures affixed to the flexible circuit 110. Embodiments using ball contacts can be configured to allow the ball contacts to roll during insertion/extraction of the lead, providing easier acceptance and removal of the lead.

**[0014]** A bottom casing 115 may be securely implanted or positioned on top of the flexible circuit 110. By way of example, the bottom casing 115 may be a structure dimensioned to hold the ball contacts in place on their corresponding contacts on flexible circuit 110. Particularly, in some embodiments, the bottom casing 115 may include individual receptacles 135 dimensioned to contain an individual electrode ball contact 125 in place and large enough to allow the ball contacts to roll within the receptacles 135. Furthermore, the bottom casing 115 may have cut-outs at the bottom of each receptacle 135 so as to expose the surface of ball contacts 125 with the top surface of their corresponding contact on flexible circuit 110. The height of the receptacles 135 can be chosen such that the top surfaces of the ball contacts extend beyond the receptacle walls. An example of this is illus-

trated in Figure 1B, which shows ball contacts 125 as being taller than the walls of receptacles 135. Although not illustrated in Figure 1B, receptacles 135 can be dimensioned with a smaller opening at the top (i.e., smaller than the diameter of the receptacle at the middle of the ball contacts) so that the receptacles 135 can hold the ball contacts in place on the contacts of flexible circuit 110.

**[0015]** Additionally, the bottom casing 115 may be configured so that a cover member 120 is securely fitted on top of the bottom casing 115. Furthermore, the cover member 120 may also detach from the bottom casing 115, which may allow a user or a medical professional to remove or replace the ball contacts 125 as needed.

**[0016]** In some configurations, the cover member 120 is dimensioned such that when there is no lead inserted in lead connector 100, there is unobstructed space directly above the ball contacts 125, as more clearly depicted in Figure 1B. In such embodiments, when there is no lead inserted in lead connector 100 the ball contacts 125 may or may not be touching the flexible circuit 110.

**[0017]** The cover member 120 may include an opening 130 on either or both ends of the cover member 120. The opening 130 may be configured to receive and guide a lead (not shown here) through the cover member 120 of the lead connector 100. Opening 130 may extend the entire length of cover member 120, or it may extend only part way through cover member 120. In some embodiments, the length of opening 130 is dimensioned such that it also forms a lead placement stop for the lead being inserted into the opening. For example, the lead placement stop (e.g., the end of the opening) may be positioned such that when the lead is inserted into the opening 130 far enough such that the lead hits the stop, the lead contacts are lined up with the lead connector contacts. In further embodiments, the lead itself can include a lead stop (such as, for example, a ring around the outer circumference of the lead) that can limit the amount by which the lead can be inserted into the lead connector housing. That is, the lead stop can be configured to contact the outer surface of cover member 120 when the lead is fully inserted.

**[0018]** Figure 2 is a diagram illustrating a side view of an example lead connector 200 in accordance with one embodiment of the technology described herein. This diagram illustrates an electrode ball contact 215 placed within a lead connector 200 as viewed through the opening. As illustrated in this example, the electrode ball contact 215 may be free to float within the bottom casing 220 and cover member 205 areas when a lead (not shown here) is not placed through the opening 210. Although the ball contacts 215 may float vertically, in some embodiments they are restrained from horizontal movement by the walls of the receptacles in bottom casing 220 (e.g., the receptacles 135 of Figure 1). Thus, the electrode ball contact 215 may not make complete contact or be electrically engaged with the flexible circuit 230 located directly beneath the bottom casing 220. In some embodi-

ments, the height of the opening between the top of the receptacle walls and the ceiling, or inner surface, of cover member 205 is large enough to admit a lead but small enough so that the ball contacts do not escape from their respective receptacles.

**[0019]** Figure 3A is a diagram illustrating a lead connector 300 in an engaged state where a lead 305 is inserted in accordance with one embodiment of the technology described herein. Figure 3B illustrates a side view of the lead connector 300 illustrated in Figure 3A. An engaged state for purposes of this application may be used to indicate that a lead 305 is inserted into the lead connector 300 through the opening 320 located on both sides of the cover member 310.

**[0020]** Referring now to Figures 3A and 3B, the lead 305 may include an array of electrical contacts 315 disposed along the length of an end portion of the lead 305. In the illustrated example, there are eight electrical contacts provided as bands of conductive material that wrap completely around the lead. Each contact may be individually electrically connected to a separate internal conductor to provide, in this case, eight communication paths. Having the contacts wrap entirely around the lead allows freedom of orientation (e.g., rotational freedom) when placing the lead into the lead connector. In other embodiments, other contact configurations can be provided on the lead such as, for example, a patch contact or a band that extends only partially around the lead circumference. Although eight lead contacts 315 are illustrated, other quantities of lead contacts 315 can be provided on the lead depending on the application or the need.

**[0021]** As this example illustrates, the electrical contacts 315 may be positioned to pass a signal between their corresponding conductors in the lead, through ball contacts 325 to the circuit board when the lead electrical contacts 315 are touching the electrical ball contacts 325. The lead 305 may be inserted within the opening 320 so that the lead electrical contacts 315 located are aligned to make contact with the ball contacts 325. When the lead 305 is inserted through the opening 320, the lead 305 may push the ball contacts 325 downward, causing them to make contact with the flexible circuit 330. This is more clearly depicted in Figure 3B.

**[0022]** As illustrated in Figure 3B, when the lead 305 is guided and pushed through the opening 320, the lead pushes ball contacts 325 downward to engage with the flexible circuit 330. Accordingly, the diameter of the lead (and lead contacts) may be chosen to provide a desired amount of deflection of the ball contacts 325. In some embodiments, the amount of deflection of the ball contacts 325 may be sufficient to flex flexible circuit 330 and compress base member 335 as shown in the illustrated example. Because the flexible circuit 330 and the base member 335 may both be made of a flexible material, and because they may have elastic properties, the flexible circuit 330 and the base member 335 may both conform to the contours of the ball contacts 325 when the

lead 305 is placed through the opening 320. Resistance provided by the elastic material can provide for a better electrical contact. Also, conformance of the flexible circuit to part of the surface of ball contacts 325 (i.e., the contact on the flexible circuit 300 wrapping part way around ball contact 325) can provide a greater surface area for the electrical contact than configurations in which the flexible circuit 300 does not conform to the circumference of the ball contact 325. Additionally, by having the lead 305 push down on the ball contacts, this may further ensure that the ball contacts are properly engaged with the flexible circuit 330.

**[0023]** Figure 4 is a diagram illustrating an end view of the example lead connector where an electrode ball contact 405 is in contact with a lead 410 in accordance with one embodiment of the technology described. When comparing Figure 2 to Figure 4, where Figure 2 shows a lead connector 200 without a lead, while Figure 4 shows a lead 410 inserted within the lead connector 400 via an opening 430 on the cover member 420. As such, as the lead 410 is received through the opening 430, the diameter of the lead 410 pushes the electrode ball contact 405 downward and forces the electrode ball contact 405 to engage with the flexible circuit 435 located on top of the base member 440.

**[0024]** Figure 5 is a diagram illustrating another example of a lead connector 500 in an engaged state where a lead 505 is inserted in accordance with one embodiment of the technology described herein. In this embodiment, there are two rows of ball contacts 510 provided. By way of example only, the two rows of ball contacts 510 may be connected in parallel to one another so that when a lead 505 is inserted through the opening 515, a single electrical contact 520 may be simultaneously in contact with a pair of ball contacts 510 located on opposite sides of one another. In other embodiments, whether a single row or double row configuration, 2 or more ball contacts can be electrically connected to one another (e.g., via interconnects on the flexible circuit). Such embodiments provide multiple points of contact for a single electrical contact 520 of the lead 505, which may, for example, increase the current handling capacity of the connection. This is further illustrated in Figure 6.

**[0025]** In other embodiments, each ball contact 510 in a pair may be electrically isolated from one another so that separate signal paths may be provided. In such embodiments, separate, electrically isolated lead contacts may also be provided around the lead to facilitate the channel separation.

**[0026]** Figure 6 is a diagram illustrating a lead connector 600 with a lead 610 in contact with multiple ball contacts 605 in accordance with one embodiment of the technology described. As illustrated, when the lead 610 is inserted through the opening 615 located on the cover member 620, the lead pushes down on the ball contacts 605. Again, with the lead 610 engaged, this may force the ball contacts 605 to make contact with the flexible circuit 630 located on top of the base member 635, and

thus securing an engaged electrical connection from the electrical contacts on the lead 610 to the flexible circuit 630. Depending on the diameters of the lead and the ball contacts 605, sufficient downforce may be provided to flex flexible circuit 630 and compress base member 635.

**[0027]** Although the base member (e.g. base member 635) is described as comprising an elastomeric, foam, or other like material, other base structures can be used to allow the ball contacts to deflect upon insertion of the lead yet provide force to maintain good electrical contact between the ball contacts in the lead contacts. As one example, the flexible circuit can be mounted on a metal or plastic or other plate that flexes sufficiently to allow the ball contacts to deflect for lead insertion, yet is sufficiently resistant to such flexion so that sufficient electrical contact is made between the ball contacts and the electrical contacts on the lead. As another example, a backing plate can be mounted under the circuit board (or provided as a base of the circuit board) with one edge attached to a housing, such that the backing plate provides a cantilevered spring-like mechanism under the circuit board. Materials can be chosen such that the backing plate deflects sufficiently to allow the lead to be inserted into the connector, while providing sufficient pressure on the ball contacts so that they make good electrical contact with the lead contacts.

**[0028]** As a further example, springs can be provided beneath the circuit board. Figure 7 is a diagram illustrating a lead connector 700 with springs beneath the metal ball contacts 710 in accordance with one embodiment of the technology described. The springs 720 may be compression springs that are each located underneath the multiple lead connector contacts 710. By way of example, the springs 720 implemented may be of various shapes and sizes, such as conical, cylindrical, hourglass, and barrel-shaped springs. The springs 720 may facilitate the electrical contact of the lead connector contacts 710 with the flexible circuit 715, and when the lead 705 is inserted through the lead connector 700, the lead 705 may push the lead connector contacts 710 into the flexible circuit and simultaneously cause the springs 720 underneath to compress while providing sufficient force in opposition to allow the lead connector contacts 710 to make sufficient electrical contact with the lead contacts 725. Although the illustrated example shows one spring aligned with each contact, as another example, the circuit board may be a rigid board and one or more springs mounted to apply pressure against the circuit board.

**[0029]** While various embodiments of the disclosed technology have been described above, it should be understood that they have been presented by way of example only, and not of limitation. Likewise, the various diagrams may depict an example architectural or other configuration for the disclosed technology, which is done to aid in understanding the features and functionality that can be included in the disclosed technology. The disclosed technology is not restricted to the illustrated example architectures or configurations, but the desired

features can be implemented using a variety of alternative architectures and configurations. Indeed, it will be apparent to one of skill in the art how alternative functional, logical or physical partitioning and configurations can be implemented to implement the desired features of the technology disclosed herein. Also, a multitude of different constituent module names other than those depicted herein can be applied to the various partitions. Additionally, with regard to flow diagrams, operational descriptions and method claims, the order in which the steps are presented herein shall not mandate that various embodiments be implemented to perform the recited functionality in the same order unless the context dictates otherwise.

**[0030]** Although the disclosed technology is described above in terms of various exemplary embodiments and implementations, it should be understood that the various features, aspects and functionality described in one or more of the individual embodiments are not limited in their applicability to the particular embodiment with which they are described, but instead can be applied, alone or in various combinations, to one or more of the other embodiments of the disclosed technology, whether or not such embodiments are described and whether or not such features are presented as being a part of a described embodiment. Thus, the breadth and scope of the technology disclosed herein should not be limited by any of the above-described exemplary embodiments.

**[0031]** Terms and phrases used in this document, and variations thereof, unless otherwise expressly stated, should be construed as open ended as opposed to limiting. As examples of the foregoing: the term "including" should be read as meaning "including, without limitation" or the like; the term "example" is used to provide exemplary instances of the item in discussion, not an exhaustive or limiting list thereof; the terms "a" or "an" should be read as meaning "at least one," "one or more" or the like; and adjectives such as "conventional," "traditional," "normal," "standard," "known" and terms of similar meaning should not be construed as limiting the item described to a given time period or to an item available as of a given time, but instead should be read to encompass conventional, traditional, normal, or standard technologies that may be available or known now or at any time in the future. Likewise, where this document refers to technologies that would be apparent or known to one of ordinary skill in the art, such technologies encompass those apparent or known to the skilled artisan now or at any time in the future.

**[0032]** The presence of broadening words and phrases such as "one or more," "at least," "but not limited to" or other like phrases in some instances shall not be read to mean that the narrower case is intended or required in instances where such broadening phrases may be absent. The use of the term "module" does not imply that the components or functionality described or claimed as part of the module are all configured in a common package. Indeed, any or all of the various components of a

module, whether control logic or other components, can be combined in a single package or separately maintained and can further be distributed in multiple groupings or packages or across multiple locations.

**[0033]** Additionally, the various embodiments set forth herein are described in terms of exemplary block diagrams, flow charts and other illustrations. As will become apparent to one of ordinary skill in the art after reading this document, the illustrated embodiments and their various alternatives can be implemented without confinement to the illustrated examples. For example, block diagrams and their accompanying description should not be construed as mandating a particular architecture or configuration.

## Claims

### 1. A lead connector comprising:

a base member;  
a flexible circuit disposed on the base member and comprising a plurality of electrical contacts;  
a casing comprising a bottom casing and a cover member, wherein the bottom casing comprises an array of receptacles at least partially open to a surface of the flexible circuit and aligned with corresponding electrical contacts on the printed circuit board; and  
an array of ball contacts positioned in the receptacles within the bottom casing;  
wherein when a lead is inserted through the lead connector via an opening on the cover member, the lead pushes the ball contacts downward to make electrical contact with the contacts on the flexible circuit.

2. The lead connector of claim 1, wherein the flexible circuit comprises a printed circuit board.

3. The lead connector of claim 1 or claim 2, wherein the lead comprises an array of electrical contacts to be aligned with the ball contacts.

4. The lead connector of any of claim 1 to claim 3, wherein the bottom casing comprises individual receptacles for placement of each individual ball contact.

5. The lead connector of any preceding claim, wherein the base member comprises a spring located on an opposite side of the circuit board from the array of ball contacts.

6. The lead connector of any preceding claim, wherein the base member is made of material comprising an elastomer.

7. The lead connector of claim 6, wherein the flexible circuit is configured to make an electrical connection with the ball contacts when the lead is inserted through the opening of the cover member, and optionally and preferably wherein the base member and the flexible circuit both conform to a shape of the ball contacts when the ball contacts are pushed downward by the lead. 5
8. The lead connector of any preceding claim, wherein the bottom casing comprises two rows of slot openings in parallel formation. 10
9. The lead connector of claim 8, wherein the ball contacts are each placed above the slot openings resulting in two rows of ball contacts in parallel formation, and optionally and preferably wherein a single electrical contact of the lead makes contact with two ball contacts simultaneously. 15
10. A method of using a lead connector for medical purposes comprising:  
inserting a lead into an opening of a lead connector, the lead connector comprising: 20
- a base member;  
a flexible circuit configured to support electrical connections;  
a casing comprising a bottom casing and a detachable cover member to be placed on top of the bottom casing, wherein the bottom casing comprises an array of slot openings to provide access to a surface of the flexible circuit; and  
an array of ball contacts positioned on top of the slot opening within the bottom casing; 30
- guiding the lead through a first opening on the lead connector till the lead passes through the second opening at an opposite end of the first opening; and 35
- aligning the lead with the ball contacts, such that each of the electric contacts of the lead is positioned to touch a corresponding electrode ball contact. 40
11. The method of claim 10, wherein the base member is made of material comprising an elastomer. 45
12. The method of claim 10 or claim 11, wherein the lead comprises an array of electrical contacts to be aligned with the ball contacts. 50
13. The method of claim 10 or claim 11 or claim 12, wherein the flexible circuit is configured to make an electrical connection with the ball contacts when the lead is inserted through the opening of the cover member, and optionally and preferably wherein the base member and the flexible circuit both conform to a shape of the ball contacts when the ball contacts 55
- are pushed downward by the lead.
14. The method of any of claim 10 to claim 13, wherein the bottom casing comprises two rows of slot openings in parallel formation, and optionally and preferably wherein the ball contacts are each placed above the slot openings resulting in two rows of ball contacts in parallel formation so that a single electrical contact of the lead makes contact with two ball contacts simultaneously.
15. The method of claim 12, wherein the flexible circuit comprises a printed circuit board, and optionally and preferably further comprising attaching the lead to a medical equipment.

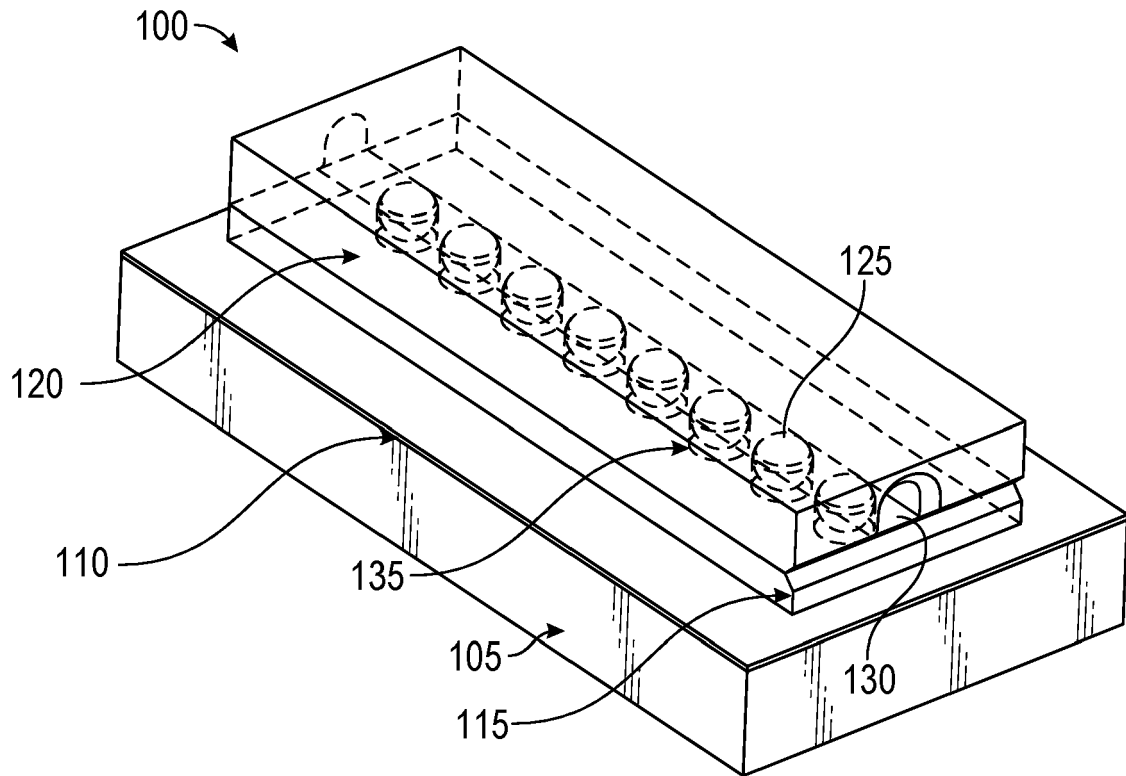


FIG. 1A

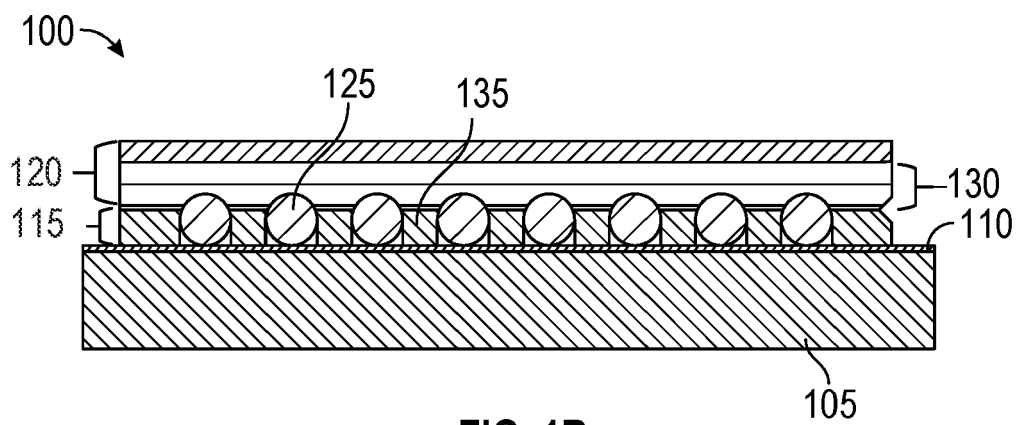
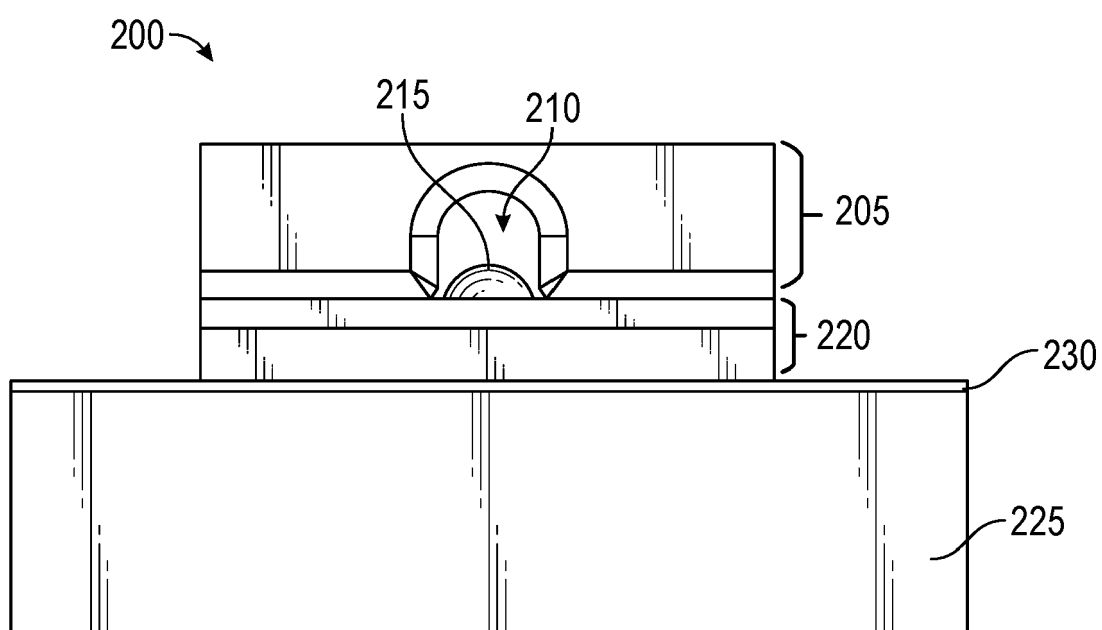


FIG. 1B





**FIG. 2**

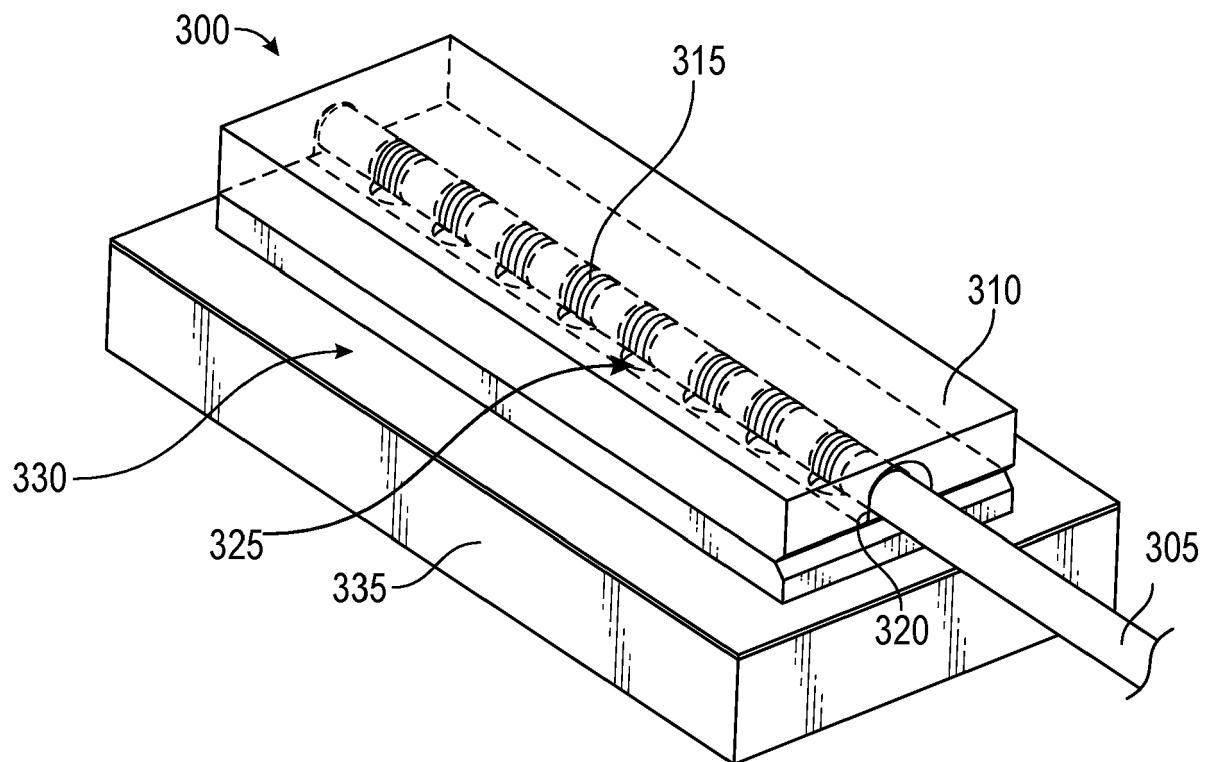


FIG. 3A

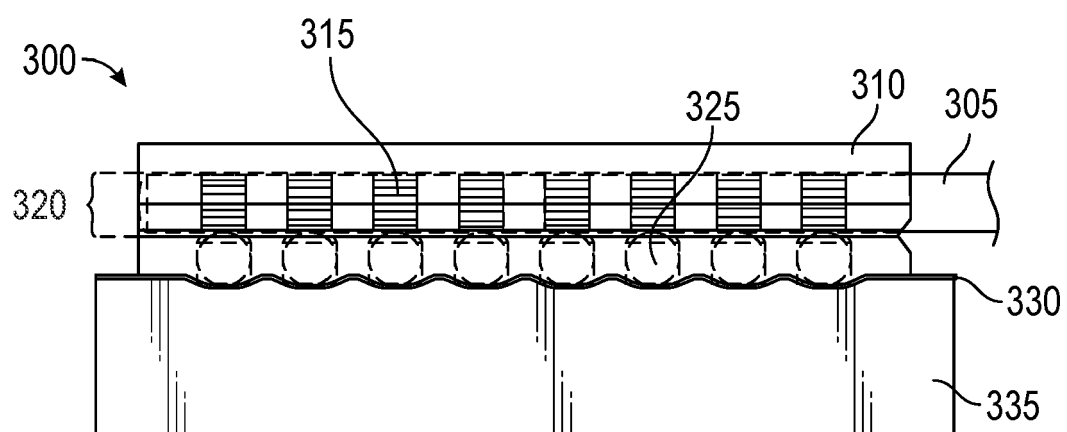


FIG. 3B

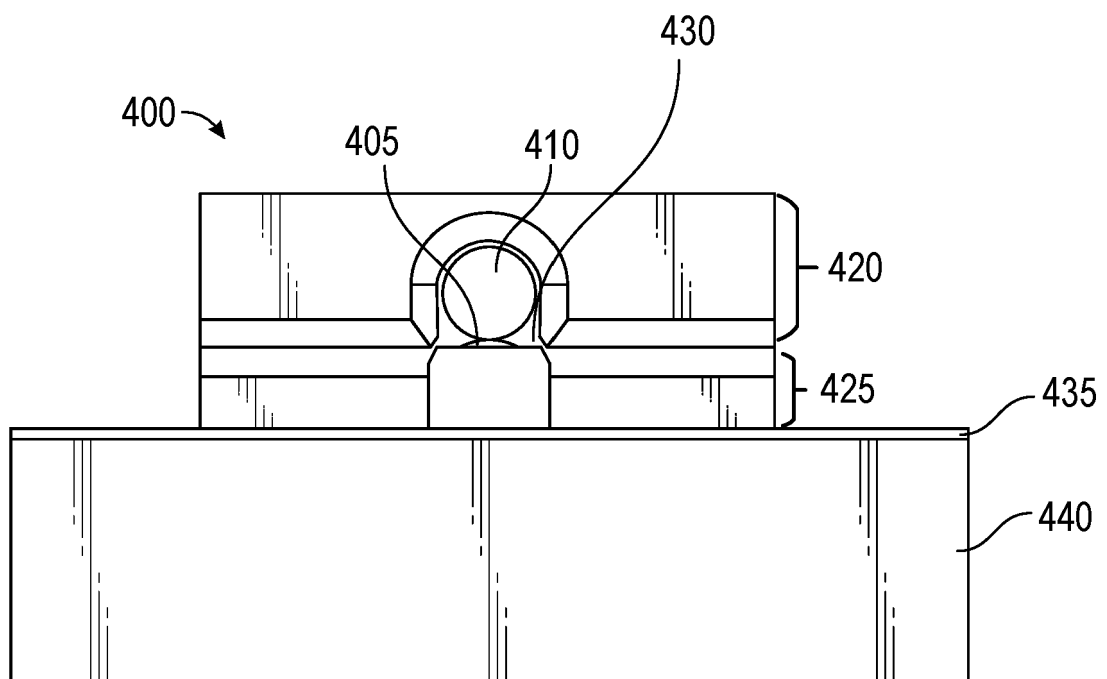


FIG. 4

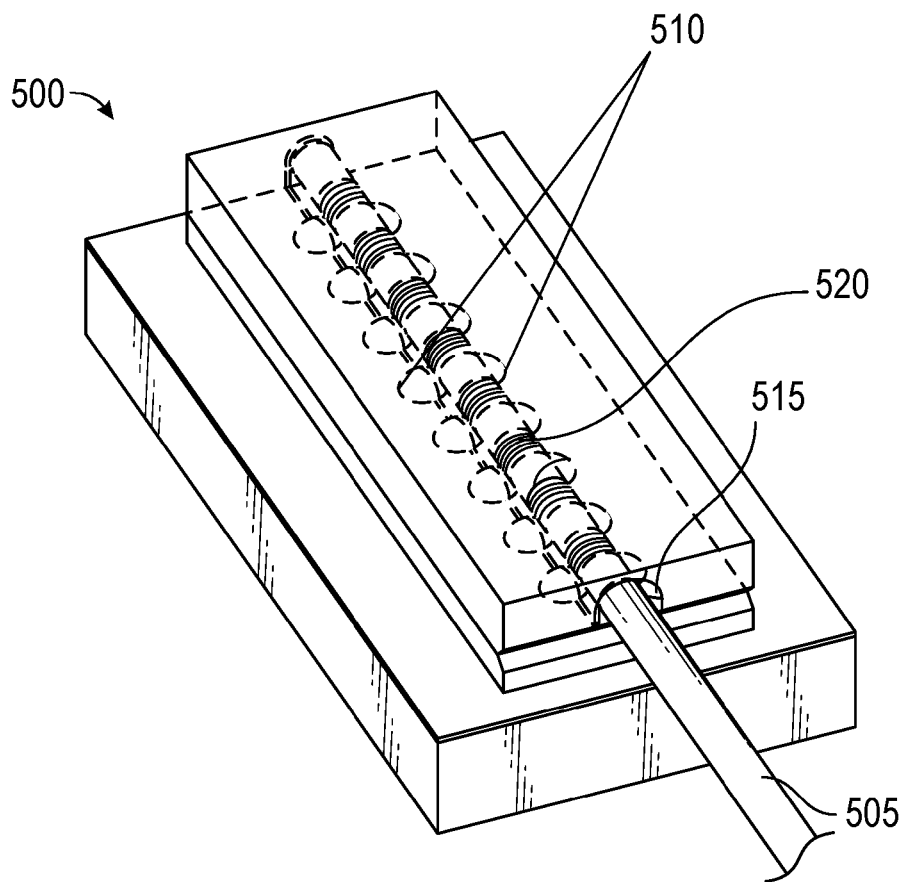


FIG. 5

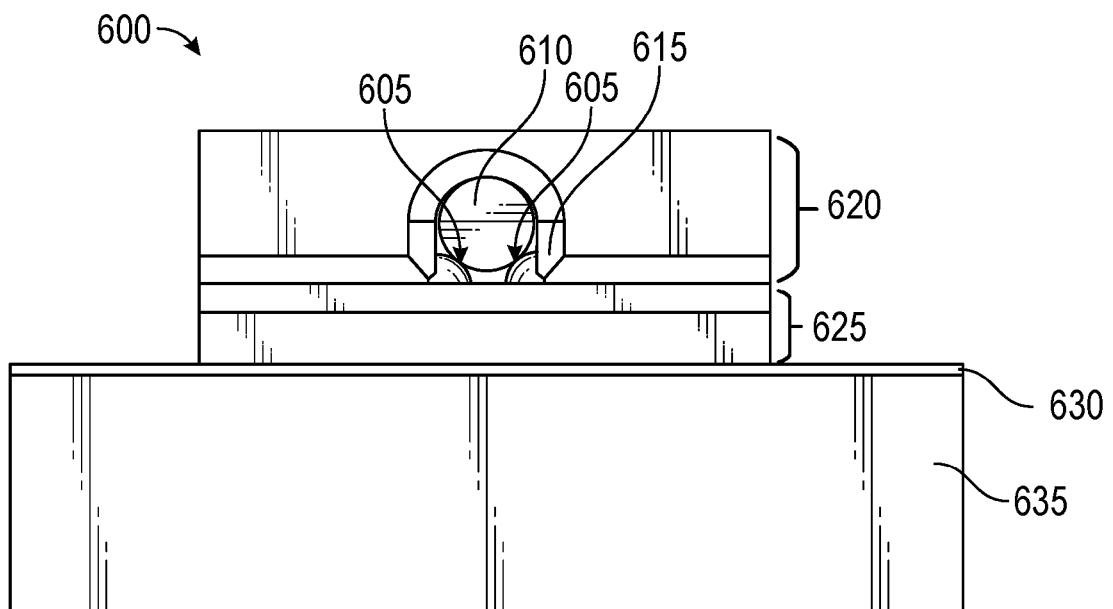


FIG. 6

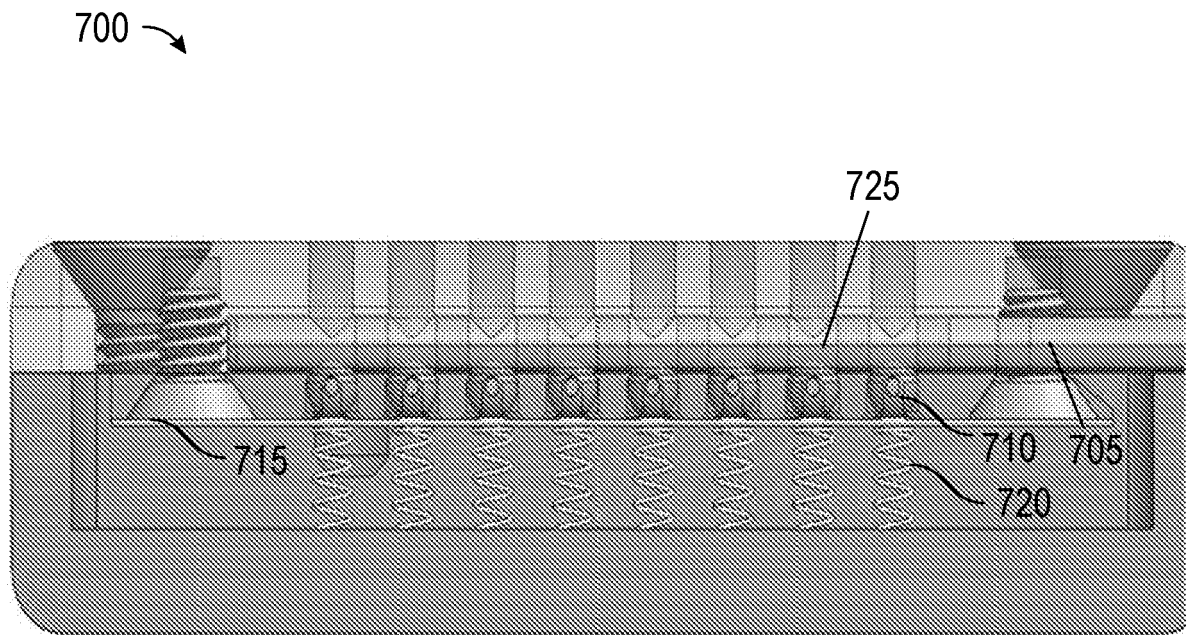


FIG. 7



## EUROPEAN SEARCH REPORT

Application Number  
EP 18 18 0869

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DOCUMENTS CONSIDERED TO BE RELEVANT			
Category	Citation of document with indication, where appropriate, of relevant passages	Relevant to claim	CLASSIFICATION OF THE APPLICATION (IPC)
A	WO 03/061469 A1 (AD TECH MEDICAL INSTR CORP [US]; PUTZ DAVID A [US]) 31 July 2003 (2003-07-31) * abstract; figures 1-7 * * page 1, lines 16-18 * * page 8, lines 15-28 * * page 9, line 12 - page 11, line 22 * -----	1-15	INV. A61N1/375
A	US 8 162 684 B1 (SOCHOR JERZY ROMAN [US]) 24 April 2012 (2012-04-24) * the whole document * -----	1-15	
A	WO 2007/109762 A1 (MEDTRONIC PARKWAY INC [US]; KAST JOHN [US]; RIES ANDREW [US]; OLSEN JI) 27 September 2007 (2007-09-27) * the whole document * -----	1-15	
A	US 2008/274651 A1 (BOYD GARTH W [US] ET AL) 6 November 2008 (2008-11-06) * the whole document * -----	1-15	
			TECHNICAL FIELDS SEARCHED (IPC)
			A61N H01R
The present search report has been drawn up for all claims			
Place of search <b>Munich</b>		Date of completion of the search <b>25 October 2018</b>	Examiner <b>Molina Silvestre, A</b>
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**ANNEX TO THE EUROPEAN SEARCH REPORT  
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